

WHAT IS CLAIMED IS:

1. A die used for sealing and molding an electronic component with a resin material, having a coating layer of nickel-tungsten alloy on at least a surface thereof contacting a melted resin material when the resin is molded.

2. The die of claim 1, wherein said coating layer is a plating layer formed of a nickel-tungsten alloy containing at least 20% by weight of tungsten.

3. The die of claim 2, wherein said coating layer has a tungsten content of at most 60% by weight.

4. The die of claim 1, wherein said coating layer is 1 μ m to 20 μ m in thickness.

5. The die of claim 1, comprising:
a fixed die;
a movable die arranged opposite to the fixed die;
upper and lower cavities provided in said fixed die and said movable die in their respective die planes to face each other along a parting-line plane of said fixed die and said movable die, for molding the resin;
a concavity receiving and setting a support having the electronic component mounted thereto;

10 a pot arranged at one of said fixed die and said movable die for supplying the resin material;

a plunger fit internal to the pot for applying pressure to the resin;
and

15 a resin channel to allow said pot and said upper cavity to communicate with each other for transporting the melted resin material,
wherein said coating layer is provided on an internal surface of said upper and lower cavities, an internal surface of said resin channel, an internal surface of said concavity, an internal surface of said pot, the

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~~parting-line plane of each of said fixed die and said movable die, and an external surface of said plunger.~~

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~~6. The die of claim 5, further comprising an ejector pin ejecting and releasing from said upper and lower cavities a resin-molded body molded in said upper and lower cavities, and an ejector pin fitting hole fitting said ejector pin therein, wherein said ejector pin has an external surface provided with said coating layer and/or said ejector pin fitting hole has an internal surface provided with said coating layer.~~

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~~7. The die of claim 5, wherein said resin channel includes a cull and a runner and gate arranged opposite to said pot for dispensing the melting resin, said cull and said runner and gate having an internal surface provided with said coating layer.~~

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~~8. The die of claim 5, further comprising an air vent allowing said upper cavity to communicate external to the die, said air vent having a surface provided with said coating layer.~~

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